

FlipChip International and Engent Announce Strategic Alliance to Develop and Deploy 3D Wafer Level CSP Technologies

PHOENIX, ARIZONA May 23rd, 2006—FlipChip International and Engent today announced a strategic alliance aimed at accelerating the development and deployment of 3D Wafer Level CSP (WLCSP) Technologies for highly integrated stacked die packaging applications. This technology has the possibility of enabling packaging solutions that are quicker to market and lower cost than System-On-Chip alternatives. Engent is a prominent leader in 3D flip chip assembly and FlipChip International is the world's leading wafer level bumping company.

This synergistic partnership couples FCI's cost-effective, high volume, ultra-fine pitch wafer bumping capabilities and 2D Wafer Level CSP package portfolio with Engent's leadership in advanced surface mount and flip chip assembly technology. The flexible technology platform emerging from this partnership supports a broad range of ultra-high volume integrated circuit packaging applications including Silicon on Silicon, GaAs on Silicon and SiGe on Silicon as well as 3D integration of emerging integrated passive device technologies and MEMS devices for System in a Stack solutions.

Bob Forcier, CEO of FlipChip International, said "We are excited about our alliance with Engent since it enables our customers to realize the cost and miniaturization benefits of 3D stacking over traditional 2D packaging. It fits perfectly with our Product and Technology Roadmaps."

Dan Baldwin, CEO of Engent, said "Our customers require both dense integration and high performance in a small form factor. Our alliance with Flip Chip International brings together a world class solution to this packaging challenge. 3D wafer level integration truly enables our customer's next generation products.

Ted Tessier, Sr. VP Engineering of FlipChip International, said, "The acceptance of WLCSP packaging technologies over the past few years has been unprecedented. The only way to go is up! This strategic alliance is a key step forward for both FCI and Engent in providing the industry with a quantum leap in packaging efficiency and flexibility".

FlipChip International, LLC is a privately-held supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market. Flip Chip International, LLC is a wholly owned subsidiary of RoseStreet Labs LLC, a supplier of products and services for the life science, renewable energy and homeland security markets.

Engent is a provider of advanced electronic manufacturing and technology services. Engent leverages its world-class facilities, highly experienced and educated team to provide solutions to a sophisticated client base which shorten a product's time to market and which enable products to be manufactured at high volumes.

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